國立清華⼤學電機資訊學院

114學年度國際半導體暨IC設計產業人才專班申請表

College of Electrical Engineering and Computer Science

National Tsing Hua University

Application Form for International Semiconductor and IC Design Program 2025

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| 1. **Personal Information 申請⼈資料**
 | Photo照片 |
|  申請件編號：(office use only) |
|  英文姓名 (as in passport)Family Name: Given Name: |
|  中文姓名 (optional) |
|  郵件帳號 |  ⽣⽇ (year/month/date)  |
|  出⽣地 | **Nationality** 國籍 |
|  護照號碼 (If applicable)  | Biological Gender 性別 : M(男) F(女) |
| Contact Information 聯絡資料 |
|  ⼾籍地址 |
| Street 街道: City 城市: Country 國家: Zip code 郵遞區號:  |
| E-mail 電子信箱:  |
| Contact Phone/Mobile Phone 電話: (country code)+(phone number ) |
|  緊急聯絡⼈ |
|  姓名:  關係:  電話:  電⼦信箱:  地址:  |

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| 1. Education Background **教育背景**
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| **Highest Degree Received**  |
| Name of Institution 學校名稱:  |
| Major in 系所: |
| School Address 學校地址Street:  |
| City:  Postal/ Zip Code: | State/ Province:Country: |
| Date of Graduation 畢業年月: (MM-DD-YYYY ) |
| Average GPA: of  |  |
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| **Others**  |
| School Name 學校名稱:  |
| Department or Focused Area 系所或專業領域: |
| School Address 學校地址Street:  |
| City:  Postal/ Zip Code: | State/ Province:Country: |
| Date of Graduation 畢業年月: (MM-DD-YYYY ) |
| Average GPA: of  |  |
|  |
| **Others** |
| School Name 學校名稱:  |
| Department or Focused Area 系所或專業領域: |
| School Address 學校地址Street:  |
| City:  Postal/ Zip Code: | State/ Province:Country: |
| Date Graduated 畢業年月: (MM-DD-YYYY ) |
| Average GPA: of  |
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| 1. **Mentionable Activity 亮點活動**
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| You may list your mentionable achievements, work experience (if any), and other relevant experiences. |
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| 1. **Other Information 其他資訊**
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|  在清華⼤學就學期間經濟來源 |
| □ Personal savings (個⼈存款)□ Other, please specify (其他，說明)□ Scholarships, please specify (獎學⾦，說明) |
|  語⾔能⼒ |
|  英文 |
| □Fluent 傑出 | □ Good 優秀 | □ Moderate 好 | □ Limited 普通 | □ None 差 |
|  中文 |
| □ Fluent 傑出 | □ Good 優秀 | □ Moderate 好 | □ Limited 普通 | □ None 差 |
|  其他語⾔: |
| □ Fluent 傑出 | □ Good 優秀 | □ Moderate 好 | □ Limited 普通 | □ None 差 |
|  住宿申請 |
|  **If available, are you interested in applying on-campus housing?** 請問是否需要申請住宿 □ Yes □ No |
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| 1. **Contacts for Recommendation Letters**
 |
| **Referee** 推薦人 1 |
| Name 姓名: |  |
| Current Position/Job Title 現職名稱: |  |
| Current Employer 現職單位: |  |
| E-mail 電⼦郵件: |  |
| Relationship with the applicant 與申請人之關係:  |  |
| **Referee** 推薦人 2 |
| Name 姓名: |  |
| Current Position/Job Title 現職名稱: |  |
| Current Employer 現職單位: |  |
| E-mail 電⼦郵件: |  |
| Relationship with the applicant與申請人之關係: |  |

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| 1. Statement of Purpose **學習計畫**
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| **Do you have preferred host professors 希望的指導教授？**  🞏 Yes 🞏 No **Have already contacted him/her 您是否已經與這位教授連繫？**  🞏 Yes 🞏 No |
| Professor’s Name 教授姓名: |
|  Department/Institute 系別: |
| E-mail 電⼦郵件: |

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| 國立清華⼤學電機資訊學院114學年度國際半導體暨IC設計產業人才專班申請表College of Electrical Engineering and Computer ScienceNational Tsing Hua UniversityApplication Form for International Semiconductor and IC Design Program 2025**Application Checking List** |
| Application Number: (office use only) |
| Applicant: |  |
| Nationality: |  |
| **NOTE** Please have the outgoing exchange program coordinator at your home institution to check your required documents and complete the following session I and II. |
| **Section I**Application Package | **List of General Required Documents** |
| 🞏 | **Application Form with Statement of Purpose** |
| 🞏 | An official copy of the **Transcript** (English) |
| 🞏 | A copy of your highest **Degree Diploma** |
| 🞏 | **Recommendation Letters** (Referees’ Contacts) |
| 🞏 | **Language Certificate** * English Proficiency Test 🞏 Chinese Proficiency Test
 |
| 🞏 | A Copy of **Passport Identity page** (valid for at least 3 months) or nationality verification |
| 🞏 | **Financial Certificate** |
| 🞏 | **Declaration Form** |
| **Section II**Applicant’s Statement | **Certification** |
| I certify that the information I have provided in this application is complete and correct. I understand that any misrepresentation, omission, or submission of false information is grounds for rejection of my application, withdrawal of acceptance, cancellation of enrollment, and/or disciplinary action at a future date. If my application is accepted, I agree to abide by the policies, rules, and regulations of the Republic of China and National Tsing Hua University. |
| **Applicant’s Signature (簽名)：\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ Date:** |